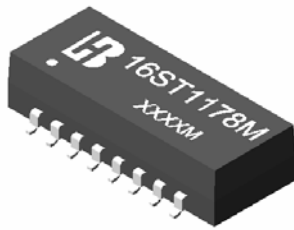


P/N: 16ST1178M DATA SHEET

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Feature



- Meets all IEEE802.3 and ANSI X3.263 standards including 350uH OCL with 8mA Bias.
- IC grade transfer-molded package suitable for reflow soldering temperatures up to 235°C.
- Patented interlock base construction for high reliability.
- Operating temperature range:-40°C to +85°C.
- Storage temperature range:-40°C to +125°C.

Electrical Specifications @ 25°C

Part Number	Turns Ratio (±5%)		DCMR TX/RX(dB Min)			HI-POT (Vrms)
	RX	TX	30MHz	60MHz	100MHz	
16ST1178M	1CT:1CT	1CT:1CT	-40	-30	-25	1500

Continue

Part Number	Insertion Loss (dB Max)	Return Loss (dB Min)					Cross talk (dB Min)	
	0.3-100 MHz	0.3-30MHz	40MHz	50MHz	60-80MHz	0.3-60MHz	60-100MHz	
16ST1178M	-1.5	-18	-13.5	-11.5	-10	-45	-35	

Schematic

Mechanical

